

Ablestik

ABLEBOND 8387B

July 2010

PRODUCT DESCRIPTION

ABLEBOND 8387B provides the following product characteristics:

Technology	Epoxy
Appearance	Black
Cure	Heat cure
Product Benefits	• Non-conductive • Fast cure • Black pigmentation for blocking stray light
Application	Die attach
Typical Package Application	Optoelectronic devices

ABLEBOND 8387B nonconductive die attach adhesive has been formulated for use in high throughput die attach applications. This adhesive can be fast cured using directed heat energy or hot plate curing techniques. In conventional box or convection conveyor oven curing, it will cure at temperatures as low as 100°C.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	≥4.5
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP): Speed 5 rpm	9,500
Work Life @ 25°C, hours	48
Shelf Life @ -40°C (from date of manufacture), year	1

TYPICAL CURING PERFORMANCE

Cure Schedule

2 minutes @ 150°C

Alternative Cure Schedule

30 minutes @ 100°C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties:

Coefficient of Thermal Expansion :	
Below Tg, ppm/°C	94
Above Tg, ppm/°C	165
Glass Transition Temperature (Tg) by TMA, °C	96

Tensile Modulus, DMTA :

@ -65 °C	N/mm ² 2,840 (psi) (411,000)
@ 25 °C	N/mm ² 1,400 (psi) (203,000)
@ 100 °C	N/mm ² 580 (psi) (84,000)
@ 150 °C	N/mm ² 77 (psi) (11,000)
@ 200 °C	N/mm ² 59 (psi) (8,500)
@ 250 °C	N/mm ² 53 (psi) (7,700)

Extractable Ionic Content, @ 100°C ppm:

Chloride (Cl-)	<300
Sodium (Na+)	<10
Potassium (K+)	<5

Water Extract Conductivity, μmhos/cm	190
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TYPICAL PERFORMANCE OF CURED MATERIAL

Die Shear Strength:

2 X 2 mm Si die, MPa (psi),

Substrate	@25°C
T2 FR-2 Leadframe	27 (3900)

3 X 3 mm Si die, MPa (psi),

Substrate	@25°C
Ag/Cu leadframe	28.1 (4100)
Cu leadframe	30.5 (4400)

12.7 X 12.7 mm Si die, MPa (psi),

Substrate	@250°C
Cu leadframe	1.9 (270)

Chip Warpage vs Chip Size:

0.38 mm thick Si die on Cu leadframe @25°C, μm

Chip Size:	Warpage:
12.7 x 12.7mm	35

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

THAWING:

1. Allow container to reach room temperature before use.
2. After removing from the freezer, set the syringes to stand vertically while thawing.
3. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
4. DO NOT re-freeze. Once thawed to -40°C, the adhesive should not be re-frozen.

DIRECTIONS FOR USE

1. Thawed adhesive should be immediately placed on dispense equipment for use.
2. If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
3. Adhesive must be completely used within the products recommended work life of 48 hours.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$
 $\text{kV/mm} \times 25.4 = \text{V/mil}$
 $\text{mm} / 25.4 = \text{inches}$
 $\text{N} \times 0.225 = \text{lb}$
 $\text{N/mm} \times 5.71 = \text{lb/in}$
 $\text{N/mm}^2 \times 145 = \text{psi}$
 $\text{MPa} \times 145 = \text{psi}$
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$
 $\text{mPa}\cdot\text{s} = \text{cP}$

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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Reference 0.1